

Amendments to the Claims

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims

1. (withdrawn) A nanoprinting apparatus for heating and pressing a substrate and a mold on which a fine concave-convex pattern is formed, in order to form a fine structure on said substrate, said apparatus further comprising a mechanism for forming a mold-releasing agent only on a convex portion of said mold.

2. (withdrawn) The nanoprinting apparatus according to claim 1, wherein said mold-releasing agent is formed by causing said convex portion of said mold to come into contact with a mold-release agent layer having a smaller thickness than the depth of a convex portion of said mold.

3. (withdrawn) A pattern transfer method for heating and pressing a substrate and a mold on the surface of which a fine concave-convex pattern is formed, using a nanoprinting apparatus, in order to form a fine structure on said substrate, wherein a mold-releasing agent is formed only on a convex portion of said mold.

4. (withdrawn) The pattern transfer method according to claim 3, wherein the transfer of pattern is carried out by heating and thus deforming a resin substrate or a resin film on a substrate.

5. (withdrawn) The pattern transfer method according to claim 3, wherein the transfer of pattern is carried out by pressing and molding a resin substrate or a resin film on a substrate, and then photo-curing the resin substrate or the resin film on the substrate.

6. (withdrawn) The pattern transfer method according to claim 3, wherein the transfer of pattern is carried out by irradiating a resin substrate or a resin film on a substrate with light from above a transparent mold, thereby photo-curing the resin substrate or the resin film on the substrate.

7. (currently amended) A mold for forming a fine structure on a substrate using a press machine, wherein said mold has a concave-convex pattern including a plurality of concave portions and convex portions, and a release treatment is provided only on a top surfaces of said convex portions of said mold ~~portion on the surface of said substrate.~~

8. (new) The mold according to claim 8, wherein said release treatment provides a mold-releasing layer only on said top surfaces of said convex portions of said mold, whereby said mold includes said mold-releasing layer only on said top surfaces of said convex portions.

9. (new) The mold according to claim 8, wherein said mold-releasing layer has a thickness smaller than a pattern depth of said mold.